News Release

Replisaurus and Leti Partner to Drive Innovative Metallization Technology Into Final Stages

As Company Prepares Clean ECPR Technology for Chip Market,
Leti Collaboration Will Boost Mastering Fabrication Process

KISTA, Sweden – July 7 – Replisaurus Technologies, Inc. today announced a common laboratory agreement with CEA-Leti, which maintains one of the world's leading research centers for applied electronics in Grenoble, France. The agreement marks a major step towards commercialization of Replisaurus' innovative ElectroChemical Pattern Replication (ECPR™) metallization process, and allows the company to move full speed ahead as it prepares to meet the high-volume, short cycle demands of the device interconnect market.

Under the multi-year agreement, Replisaurus and Leti personnel will collaborate and take advantage of the lab's extensive manufacturing facilities, experience in both semiconductor and MEMS technology, and expertise with 200mm and 300mm wafer technologies. The team will initially focus on optimizing the development of reusable master electrodes, a key component of the ECPR process which employs a template to fabricate metal patterns in a single replication step. They will also investigate the opportunities for ECPR in new applications, notably in key growth sectors such as integrated passives, copper pillars and 3D integration. The team will optimize electrode design and fabrication flow for each application area, ensuring the best yield, endurance and cycle time.

In order to create a platform to build its mastering business, Replisaurus has started a new company called Replisaurus Mastering, and the program is already up and running at Leti's facility in Grenoble.

"The mastering process is a central part of our business model and a unique component of our technology, so Leti's practical, business-oriented approach to IP rights was a major factor in our decision to partner with them," said James Quinn, CEO of Replisaurus. "We are moving forward according to plans to roll out our technology, and through this partnership Leti will support us in transferring it to a foundry partner."

The ECPR process reduces metallization complexity and accelerates production by eliminating many steps from the traditional process. ECPR also provides improved patterning and significant cost and time savings, with a fab-friendly, environmentally clean process that doesn't use solvents or strippers. Along with its significant environmental benefits, ECPR reduces metallization complexity, boosts production speed, and represents a genuine step forward for the chip industry.

"This new project with Replisaurus is a very exciting challenge as we help integrate its innovative clean metallization technology into a high-volume manufacturing solution. All of the necessary technical developments are already underway, and this collaboration got off to a great start," said Laurent Malier, general manager of CEA-Leti. "In addition, access to ECPR technology through this agreement will enable Leti to position itself at the leading edge of research into advanced interconnect and device packaging technologies for diverse applications."

The development program will explore 3D technology and applications and employ technology from Replisaurus subsidiary SET, including the FC300, a high-accuracy, high force device bonder system for die-to-die and die-to-wafer bonding on wafers up to 300mm.

"CEA-Leti has advanced capabilities with CMOS and MEMS applications that will be a great testbed for our technology as we look to apply it in other application areas," said Alan Cuthbertson, vice president of Mastering Technology at Replisaurus. "We will focus on 200mm silicon and 300mm through this project and Leti's world-class facility is the perfect place to enhance our technology for the chip market."

About Replisaurus Technologies

Replisaurus Technologies, Inc. has developed a revolutionary metallization technology targeted at key growth markets such as integrated passives, copper pillars and 3D integration (TSV). The ElectroChemical Pattern Replication (ECPR™) process offers a simple and cost effective integrated solution eliminating several traditional process steps thereby reducing complexity. ECPR is a fab-friendly, environmentally clean process which does not use any solvents, developers or strippers and has extremely fast plating rates. In 2008, Replisaurus acquired SET, a world leading supplier of high accuracy die-to-die, die-to-wafer bonding and nanoimprint lithography solutions. For more information visit www.replisaurus.com.

About CEA-Leti

CEA is a French public research and technology organisation, with activities in three main areas: Energy, Technologies for Information and Healthcare, and Defence and Security. Within CEA, the Laboratory for Electronics & Information Technology (Leti) works with companies in order to increase their competitiveness through technological innovation and transfers. Leti is focused on micro and nanotechnologies and their applications, from wireless devices and systems, to biology and healthcare or photonics. Nanoelectronics and Microsystems (MEMS) are at the core of its activities. As a major player in MINATEC excellence centre, Leti operates 8,000 m² state-of-the-art clean rooms, in 24/7 mode, on 200 mm and 300 mm wafer standards. With 1,200 employees, Leti trains more than 150 Ph.D. students and hosts 200 assignees from partner companies. Strongly committed to the creation of value for the industry, Leti puts a strong emphasis on Intellectual Property and owns more than 1,400 patent families. In 2008, contractual income covered more than 75% of its budget worth 205 M€. For more information, visit www.leti.fr.

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